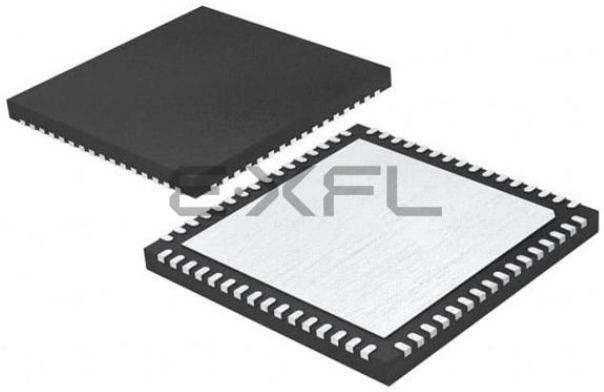
Microchip Technology - DSPIC33FJ256GP506AT-I/MR Datasheet



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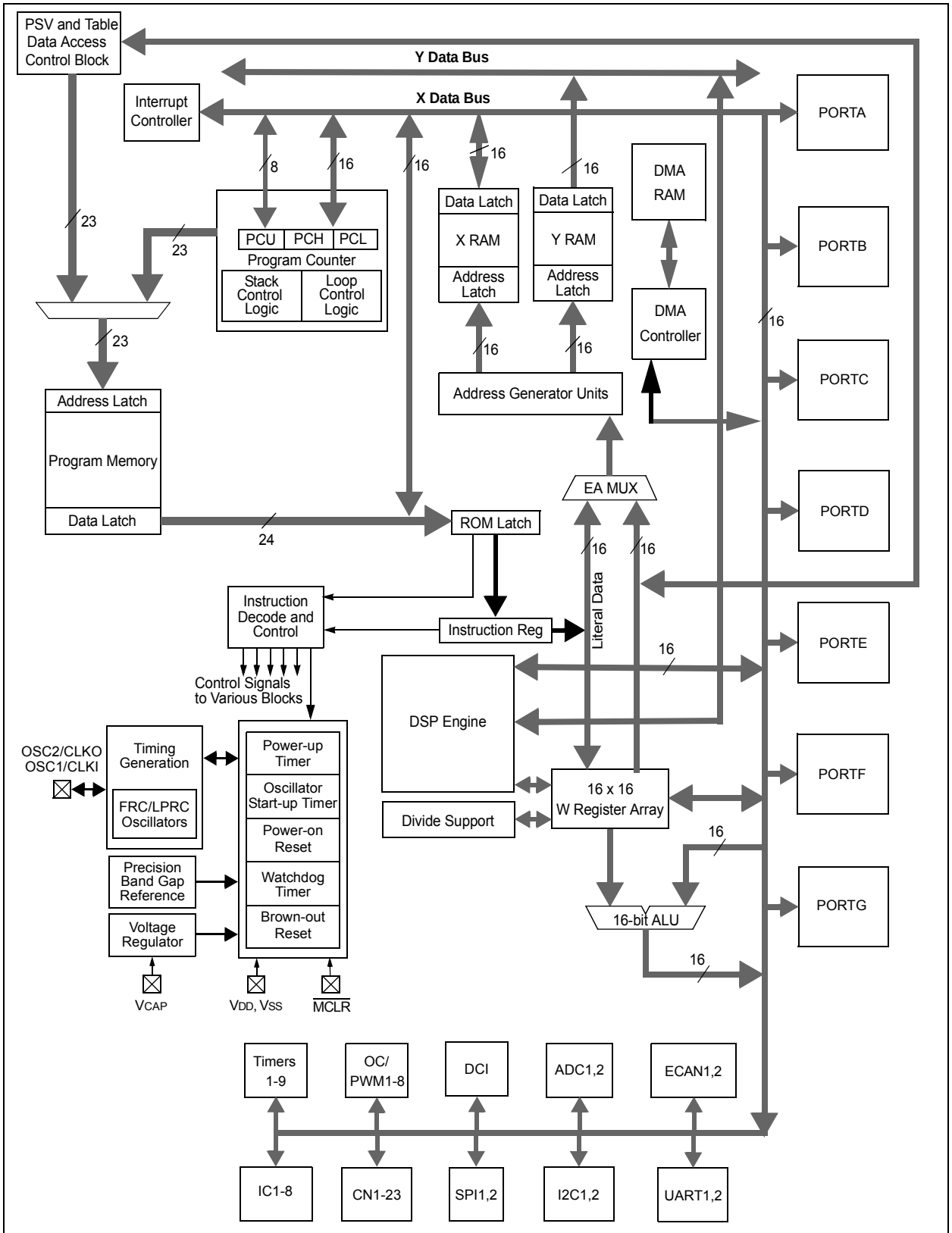
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	AC'97, Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	53
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 18x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj256gp506at-i-mr

FIGURE 1-1: dsPIC33FJXXXGPX06A/X08A/X10A GENERAL BLOCK DIAGRAM



Note: Not all pins or features are implemented on all device pinout configurations. See the **"Pin Diagrams"** section for the specific pins and features present on each device.

REGISTER 3-1: SR: CPU STATUS REGISTER

bit 8 **DC:** MCU ALU Half Carry/$\overline{\text{Borrow}}$ bit
1 = A carry-out from the 4th low-order bit (for byte sized data) or 8th low-order bit (for word sized data) of the result occurred
0 = No carry-out from the 4th low-order bit (for byte sized data) or 8th low-order bit (for word sized data) of the result occurred

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(2)
111 = CPU Interrupt Priority Level is 7 (15), user interrupts disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

bit 4 **RA:** REPEAT Loop Active bit
1 = REPEAT loop in progress
0 = REPEAT loop not in progress

bit 3 **N:** MCU ALU Negative bit
1 = Result was negative
0 = Result was non-negative (zero or positive)

bit 2 **OV:** MCU ALU Overflow bit
This bit is used for signed arithmetic (2's complement). It indicates an overflow of the magnitude which causes the sign bit to change state.
1 = Overflow occurred for signed arithmetic (in this arithmetic operation)
0 = No overflow occurred

bit 1 **Z:** MCU ALU Zero bit
1 = An operation which affects the Z bit has set it at some time in the past
0 = The most recent operation which affects the Z bit has cleared it (i.e., a non-zero result)

bit 0 **C:** MCU ALU Carry/$\overline{\text{Borrow}}$ bit
1 = A carry-out from the Most Significant bit of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note 1: This bit may be read or cleared (not set).
2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.
3: The IPL<2:0> Status bits are read only when NSTDIS = 1 (INTCON1<15>).

REGISTER 7-29: IPC14: INTERRUPT PRIORITY CONTROL REGISTER 14

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	DCIEIP<2:0>			—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	C2IP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **DCIEIP<2:0>:** DCI Error Interrupt Priority bits

111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 11-3 **Unimplemented:** Read as '0'

bit 2-0 **C2IP<2:0>:** ECAN2 Event Interrupt Priority bits

111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

REGISTER 9-2: CLKDIV: CLOCK DIVISOR REGISTER(2)

R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
ROI	DOZE<2:0>			DOZEN(1)	FRCDIV<2:0>		
bit 15							bit 8

R/W-0	R/W-1	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PLLPOST<1:0>		—	PLLPRE<4:0>				
bit 7							bit 0

Legend:	y = Value set from Configuration bits on POR		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROI:** Recover on Interrupt bit
1 = Interrupts will clear the DOZEN bit and the processor clock/peripheral clock ratio is set to 1:1
0 = Interrupts have no effect on the DOZEN bit

bit 14-12 **DOZE<2:0>:** Processor Clock Reduction Select bits
111 = FCY/128
110 = FCY/64
101 = FCY/32
100 = FCY/16
011 = FCY/8 (default)
010 = FCY/4
001 = FCY/2
000 = FCY/1

bit 11 **DOZEN:** DOZE Mode Enable bit(1)
1 = DOZE<2:0> field specifies the ratio between the peripheral clocks and the processor clocks
0 = Processor clock/peripheral clock ratio forced to 1:1

bit 10-8 **FRCDIV<2:0>:** Internal Fast RC Oscillator Postscaler bits
111 = FRC divide by 256
110 = FRC divide by 64
101 = FRC divide by 32
100 = FRC divide by 16
011 = FRC divide by 8
010 = FRC divide by 4
001 = FRC divide by 2
000 = FRC divide by 1 (default)

bit 7-6 **PLLPOST<1:0>:** PLL VCO Output Divider Select bits (also denoted as 'N2', PLL postscaler)
11 = Output/8
10 = Reserved
01 = Output/4 (default)
00 = Output/2

bit 5 **Unimplemented:** Read as '0'

bit 4-0 **PLLPRE<4:0>:** PLL Phase Detector Input Divider bits (also denoted as 'N1', PLL prescaler)
11111 = Input/33
•
•
•
00001 = Input/3
00000 = Input/2 (default)

Note 1: This bit is cleared when the ROI bit is set and an interrupt occurs.
2: This is register is reset only on a Power-on Reset (POR).

16.1 SPI Helpful Tips

1. In Frame mode, if there is a possibility that the master may not be initialized before the slave:
   a) If FRMPOL (SPIxCON2<13>) = 1, use a pull-down resistor on $\overline{SSx}$.
   b) If FRMPOL = 0, use a pull-up resistor on $\overline{SSx}$.

Note:	This insures that the first frame transmission after initialization is not shifted or corrupted.

2. In non-framed 3-wire mode, (i.e., not using $\overline{SSx}$ from a master):
   a) If CKP (SPIxCON1<6>) = 1, always place a pull-up resistor on $\overline{SSx}$.
   b) If CKP = 0, always place a pull-down resistor on $\overline{SSx}$.

Note:	This will insure that during power-up and initialization the master/slave will not lose sync due to an errant SCK transition that would cause the slave to accumulate data shift errors for both transmit and receive appearing as corrupted data.

3. FRMEN (SPIxCON2<15>) = 1 and SSEN (SPIxCON1<7>) = 1 are exclusive and invalid. In Frame mode, SCKx is continuous and the Frame sync pulse is active on the $\overline{SSx}$ pin, which indicates the start of a data frame.

Note:	Not all third-party devices support Frame mode timing. Refer to the SPI electrical characteristics for details.

4. In Master mode only, set the SMP bit (SPIxCON1<9>) to a '1' for the fastest SPI data rate possible. The SMP bit can only be set at the same time or after the MSTEN bit (SPIxCON1<5>) is set.
5. To avoid invalid slave read data to the master, the user's master software must guarantee enough time for slave software to fill its write buffer before the user application initiates a master write/read cycle. It is always advisable to preload the SPIxBUF transmit register in advance of the next master transaction cycle. SPIxBUF is transferred to the SPI shift register and is empty once the data transmission begins.

16.2 SPI Resources

Many useful resources related to SPI are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en546064

16.2.1 KEY RESOURCES

- **Section 18. "Serial Peripheral Interface (SPI)"** (DS70206)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

REGISTER 19-10: CiCFG2: ECAN™ BAUD RATE CONFIGURATION REGISTER 2

U-0	R/W-x	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	WAKFIL	—	—	—	SEG2PH<2:0>		
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SEG2PHTS	SAM	SEG1PH<2:0>			PRSEG<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14 **WAKFIL:** Select CAN bus Line Filter for Wake-up bit
1 = Use CAN bus line filter for wake-up
0 = CAN bus line filter is not used for wake-up

bit 13-11 **Unimplemented:** Read as '0'

bit 10-8 **SEG2PH<2:0>:** Phase Buffer Segment 2 bits
111 = Length is 8 x TQ
000 = Length is 1 x TQ

bit 7 **SEG2PHTS:** Phase Segment 2 Time Select bit
1 = Freely programmable
0 = Maximum of SEG1PH bits or Information Processing Time (IPT), whichever is greater

bit 6 **SAM:** Sample of the CAN bus Line bit
1 = Bus line is sampled three times at the sample point
0 = Bus line is sampled once at the sample point

bit 5-3 **SEG1PH<2:0>:** Phase Buffer Segment 1 bits
111 = Length is 8 x TQ
000 = Length is 1 x TQ

bit 2-0 **PRSEG<2:0>:** Propagation Time Segment bits
111 = Length is 8 x TQ
000 = Length is 1 x TQ

REGISTER 19-19: CiFMSKSEL2: ECAN™ FILTER 15-8 MASK SELECTION REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F15MSK<1:0>		F14MSK<1:0>		F13MSK<1:0>		F12MSK<1:0>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F11MSK<1:0>		F10MSK<1:0>		F9MSK<1:0>		F8MSK<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **F15MSK<1:0>:** Mask Source for Filter 15 bit
11 = Reserved; do not use
10 = Acceptance Mask 2 registers contain mask
01 = Acceptance Mask 1 registers contain mask
00 = Acceptance Mask 0 registers contain mask

bit 13-12 **F14MSK<1:0>:** Mask Source for Filter 14 bit
11 = Reserved; do not use
10 = Acceptance Mask 2 registers contain mask
01 = Acceptance Mask 1 registers contain mask
00 = Acceptance Mask 0 registers contain mask

bit 11-10 **F13MSK<1:0>:** Mask Source for Filter 13 bit
11 = Reserved; do not use
10 = Acceptance Mask 2 registers contain mask
01 = Acceptance Mask 1 registers contain mask
00 = Acceptance Mask 0 registers contain mask

bit 9-8 **F12MSK<1:0>:** Mask Source for Filter 12 bit
11 = Reserved; do not use
10 = Acceptance Mask 2 registers contain mask
01 = Acceptance Mask 1 registers contain mask
00 = Acceptance Mask 0 registers contain mask

bit 7-6 **F11MSK<1:0>:** Mask Source for Filter 11 bit
11 = Reserved; do not use
10 = Acceptance Mask 2 registers contain mask
01 = Acceptance Mask 1 registers contain mask
00 = Acceptance Mask 0 registers contain mask

bit 5-4 **F10MSK<1:0>:** Mask Source for Filter 10 bit
11 = Reserved; do not use
10 = Acceptance Mask 2 registers contain mask
01 = Acceptance Mask 1 registers contain mask
00 = Acceptance Mask 0 registers contain mask

bit 3-2 **F9MSK<1:0>:** Mask Source for Filter 9 bit
11 = Reserved; do not use
10 = Acceptance Mask 2 registers contain mask
01 = Acceptance Mask 1 registers contain mask
00 = Acceptance Mask 0 registers contain mask

bit 1-0 **F8MSK<1:0>:** Mask Source for Filter 8 bit
11 = Reserved; do not use
10 = Acceptance Mask 2 registers contain mask
01 = Acceptance Mask 1 registers contain mask
00 = Acceptance Mask 0 registers contain mask

REGISTER 19-20: CiRXMnSID: ECAN™ ACCEPTANCE FILTER MASK n STANDARD IDENTIFIER

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID<10:3>							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	U-0	R/W-x	U-0	R/W-x	R/W-x
SID<2:0>			—	MIDE	—	EID<17:16>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **SID<10:0>:** Standard Identifier bits
1 = Include bit SIDx in filter comparison
0 = Bit SIDx is don't care in filter comparison

bit 4 **Unimplemented:** Read as '0'

bit 3 **MIDE:** Identifier Receive Mode bit
1 = Match only message types (standard or extended address) that correspond to EXIDE bit in filter
0 = Match either standard or extended address message if filters match
(i.e., if (Filter SID) = (Message SID) or if (Filter SID/EID) = (Message SID/EID))

bit 2 **Unimplemented:** Read as '0'

bit 1-0 **EID<17:16>:** Extended Identifier bits
1 = Include bit EIDx in filter comparison
0 = Bit EIDx is don't care in filter comparison

REGISTER 19-21: CiRXMnEID: ECAN™ ACCEPTANCE FILTER MASK n EXTENDED IDENTIFIER

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID<15:8>							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **EID<15:0>:** Extended Identifier bits
1 = Include bit EIDx in filter comparison
0 = Bit EIDx is don't care in filter comparison

REGISTER 21-4: ADxCON4: ADCx CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	DMABL<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as ‘0’

bit 2-0 **DMABL<2:0>:** Selects Number of DMA Buffer Locations per Analog Input bits

111 = Allocates 128 words of buffer to each analog input
110 = Allocates 64 words of buffer to each analog input
101 = Allocates 32 words of buffer to each analog input
100 = Allocates 16 words of buffer to each analog input
011 = Allocates 8 words of buffer to each analog input
010 = Allocates 4 words of buffer to each analog input
001 = Allocates 2 words of buffer to each analog input
000 = Allocates 1 word of buffer to each analog input

TABLE 25-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min(1)**	**Typ**	**Max(1)**	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD transition high-to-low	2.40	—	2.55	V	VDD

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

TABLE 25-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(3)**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	10,000	—	—	E/W	
D131	VPR	VDD for Read	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D132b	VPEW	VDD for Self-Timed Write	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	
D136a	TRW	Row Write Time	1.32	—	1.74	ms	TRW = 11064 FRC cycles, TA = +85°C, See **Note 2**
D136b	TRW	Row Write Time	1.28	—	1.79	ms	TRW = 11064 FRC cycles, TA = +150°C, See **Note 2**
D137a	TPE	Page Erase Time	20.1	—	26.5	ms	TPE = 168517 FRC cycles, TA = +85°C, See **Note 2**
D137b	TPE	Page Erase Time	19.5	—	27.3	ms	TPE = 168517 FRC cycles, TA = +150°C, See **Note 2**
D138a	TWW	Word Write Cycle Time	42.3	—	55.9	µs	TWW = 355 FRC cycles, TA = +85°C, See **Note 2**
D138b	TWW	Word Write Cycle Time	41.1	—	57.6	µs	TWW = 355 FRC cycles, TA = +150°C, See **Note 2**

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: Other conditions: FRC = 7.37 MHz, TUN<5:0> = b'011111 (for Min), TUN<5:0> = b'100000 (for Max). This parameter depends on the FRC accuracy (see Table 25-19) and the value of the FRC Oscillator Tuning register (see Register 9-4). For complete details on calculating the Minimum and Maximum time see **Section 5.3 "Programming Operations"**.

3: These parameters are assured by design, but are not characterized or tested in manufacturing.

TABLE 25-13: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended							
Param.	**Symbol**	**Characteristics**	**Min**	**Typ**	**Max**	**Units**	**Comments**
—	CEFC	External Filter Capacitor Value(1)	4.7	10	—	µF	Capacitor must be low series resistance (< 5 ohms)

Note 1: Typical VCORE voltage = 2.5V when VDD ≥ VDDMIN.

TABLE 25-38: DCI MODULE (MULTI-CHANNEL, I^2S MODES) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
CS10	TCSCKL	CSCK Input Low Time (CSCK pin is an input)	TCY/2 + 20	—	—	ns	—
		CSCK Output Low Time(3) (CSCK pin is an output)	30	—	—	ns	—
CS11	TCSCKH	CSCK Input High Time (CSCK pin is an input)	TCY/2 + 20	—	—	ns	—
		CSCK Output High Time(3) (CSCK pin is an output)	30	—	—	ns	—
CS20	TCSCKF	CSCK Output Fall Time(4) (CSCK pin is an output)	—	10	25	ns	—
CS21	TCSCKR	CSCK Output Rise Time(4) (CSCK pin is an output)	—	10	25	ns	—
CS30	TCSDOF	CSDO Data Output Fall Time(4)	—	10	25	ns	—
CS31	TCSDOR	CSDO Data Output Rise Time(4)	—	10	25	ns	—
CS35	TDV	Clock Edge to CSDO Data Valid	—	—	10	ns	—
CS36	TDIV	Clock Edge to CSDO Tri-Stated	10	—	20	ns	—
CS40	TCSDI	Setup Time of CSDI Data Input to CSCK Edge (CSCK pin is input or output)	20	—	—	ns	—
CS41	THCSDI	Hold Time of CSDI Data Input to CSCK Edge (CSCK pin is input or output)	20	—	—	ns	—
CS50	TCOFSF	COFS Fall Time (COFS pin is output)	—	10	25	ns	**Note 1**
CS51	TCOFSR	COFS Rise Time (COFS pin is output)	—	10	25	ns	**Note 1**
CS55	TSCOFS	Setup Time of COFS Data Input to CSCK Edge (COFS pin is input)	20	—	—	ns	—
CS56	THCOFS	Hold Time of COFS Data Input to CSCK Edge (COFS pin is input)	20	—	—	ns	—

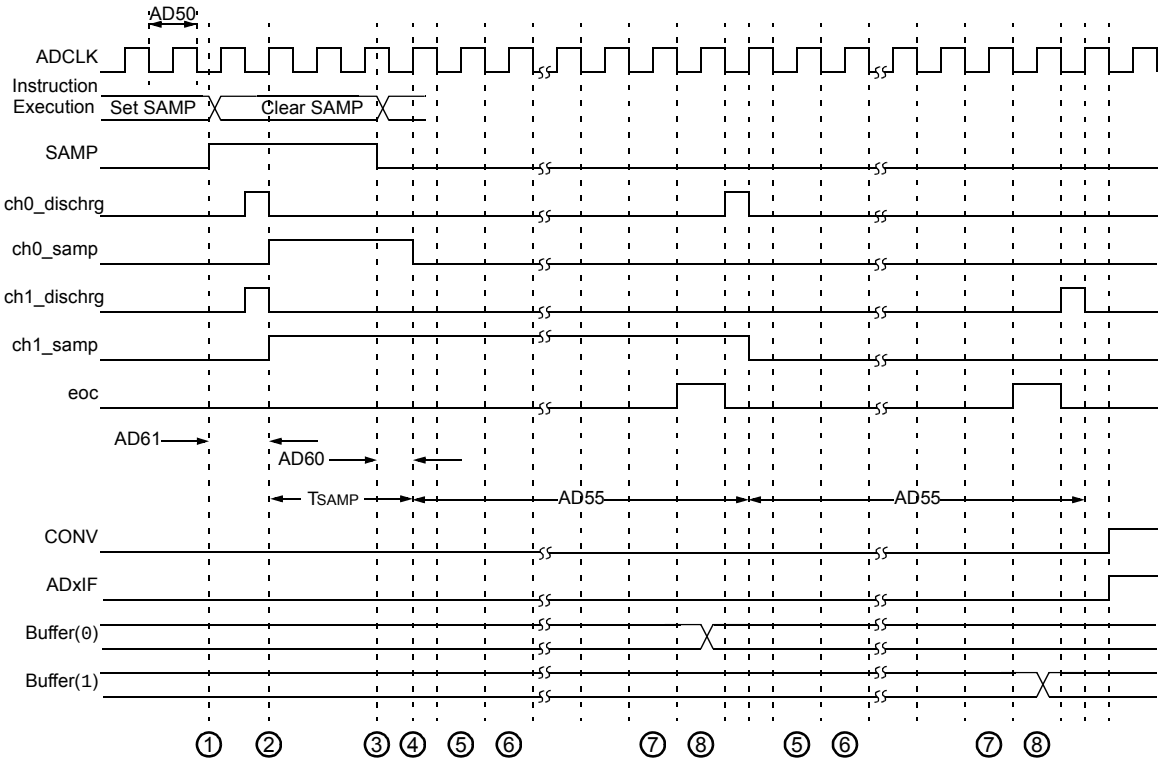
Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for CSCK is 100 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all DCI pins.

FIGURE 25-25: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000)



(1) – Software sets ADxCON. SAMP to start sampling.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33F/PIC24H Family Reference Manual"*.

(3) – Software clears ADxCON. SAMP to start conversion.

(4) – Sampling ends, conversion sequence starts.

(5) – Convert bit 9.

(6) – Convert bit 8.

(7) – Convert bit 0.

(8) – One TAD for end of conversion.

27.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note: The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 27-1: VOH – 2x DRIVER PINS

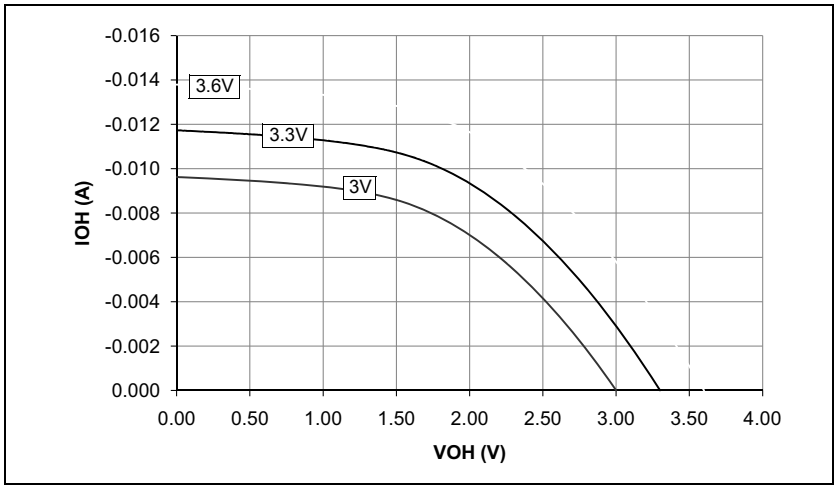


FIGURE 27-2: VOH – 4x DRIVER PINS

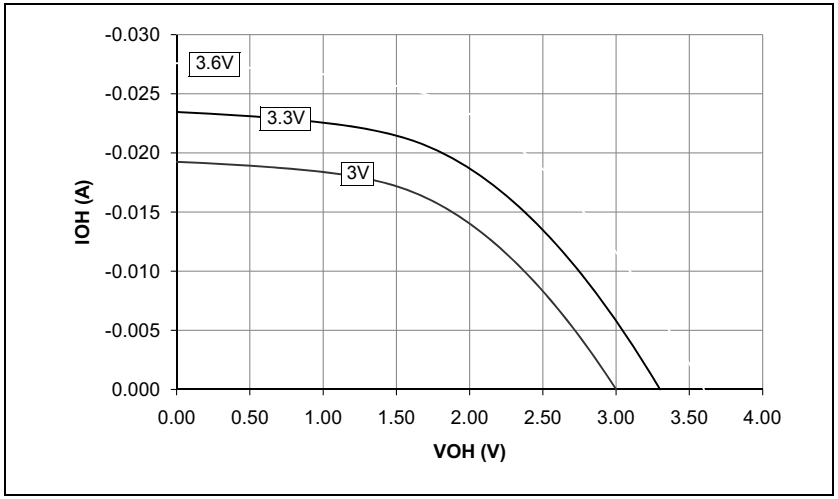


FIGURE 27-3: VOH – 8x DRIVER PINS

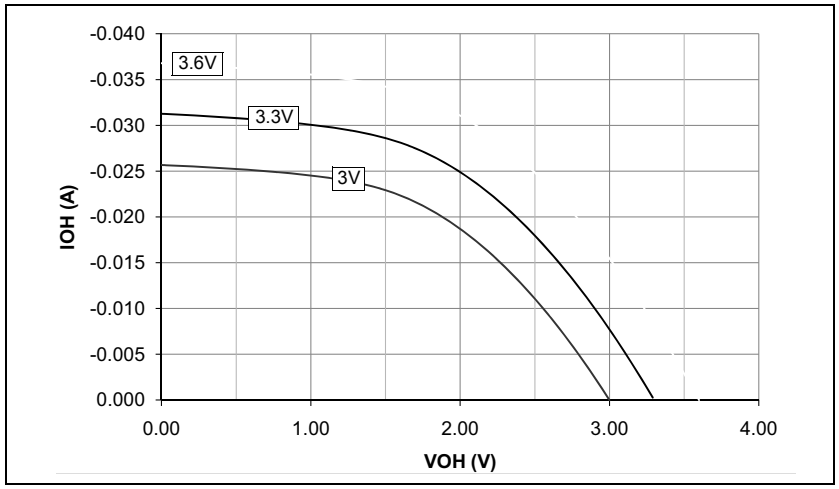
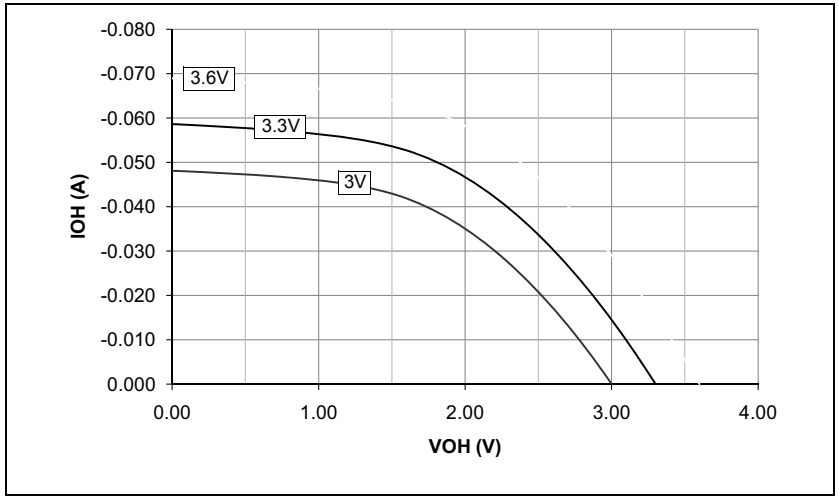
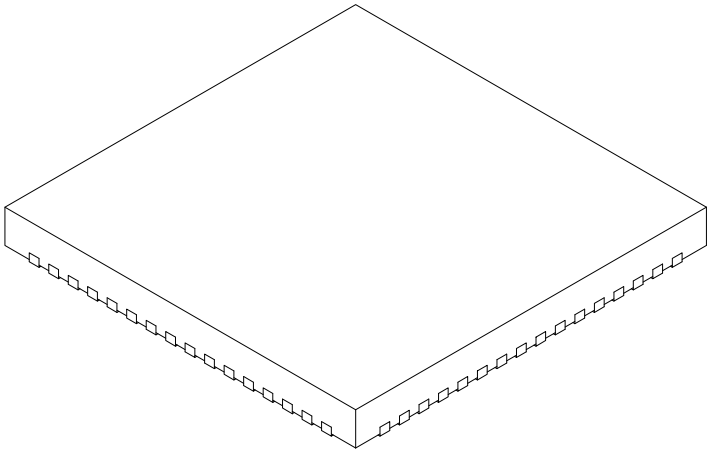


FIGURE 27-4: VOH – 16x DRIVER PINS



64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body with 5.40 x 5.40 Exposed Pad [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		64	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		9.00 BSC	
Exposed Pad Width	E2	5.30	5.40	5.50
Overall Length	D		9.00 BSC	
Exposed Pad Length	D2	5.30	5.40	5.50
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

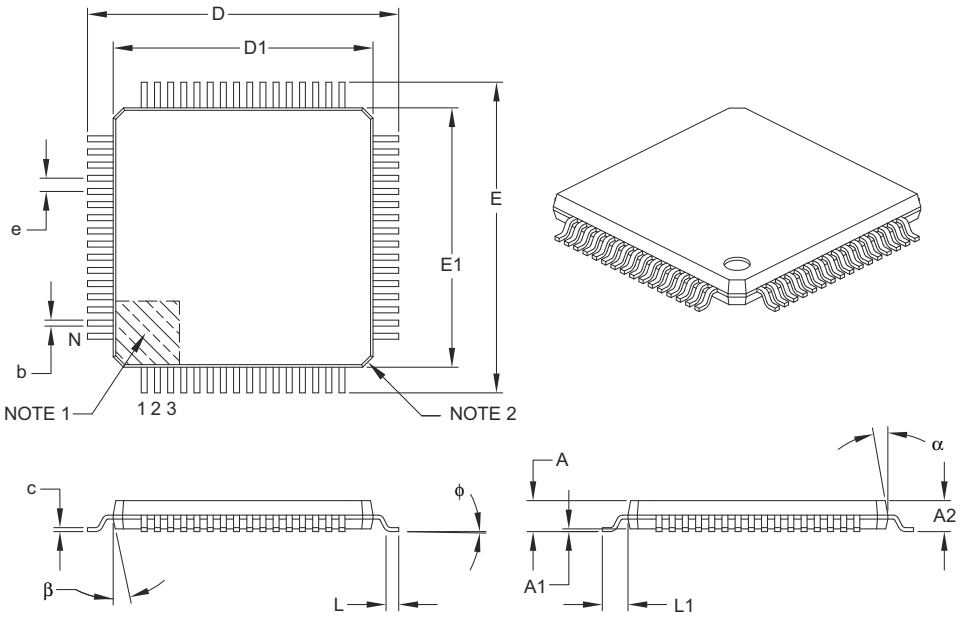
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-154A Sheet 2 of 2

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

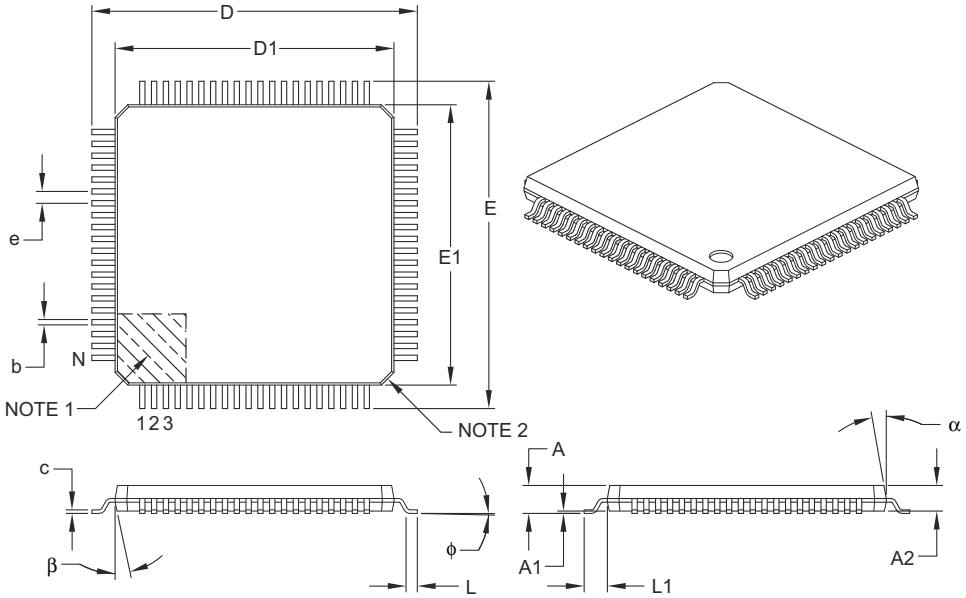
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

80-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		80	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		14.00 BSC	
Overall Length	D		14.00 BSC	
Molded Package Width	E1		12.00 BSC	
Molded Package Length	D1		12.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

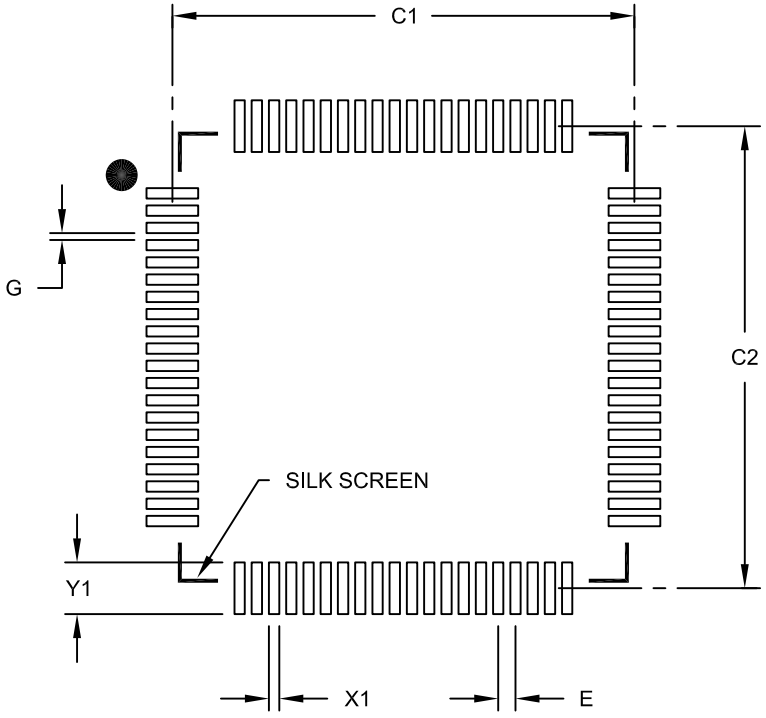
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-092B

80-Lead Plastic Thin Quad Flatpack (PT) - 12x12x1mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X80)	X1			0.30
Contact Pad Length (X80)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

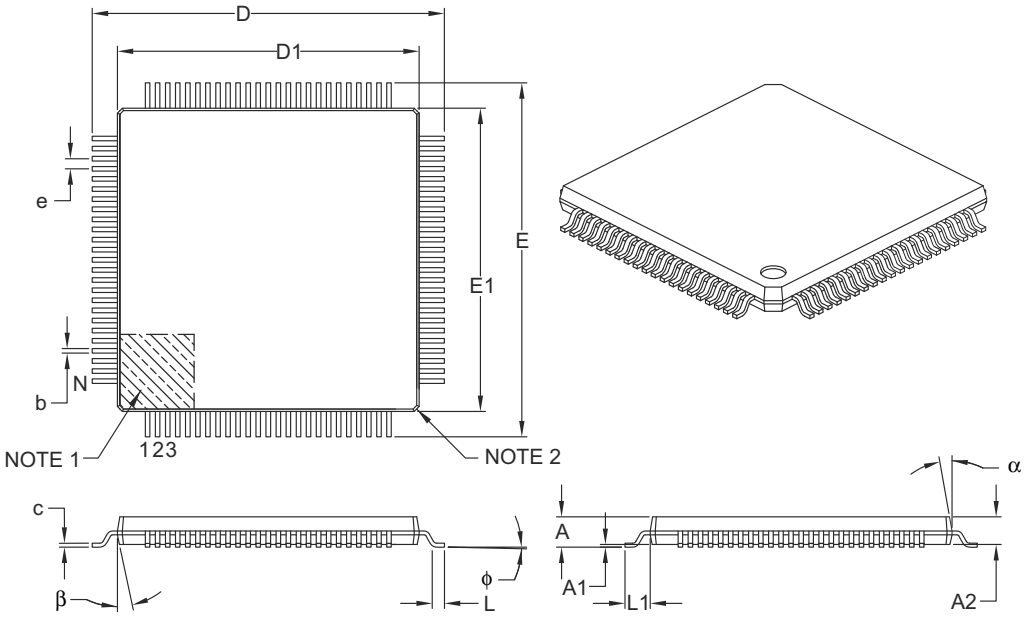
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2092B

100-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.40 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		14.00 BSC	
Overall Length	D		14.00 BSC	
Molded Package Width	E1		12.00 BSC	
Molded Package Length	D1		12.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.13	0.18	0.23
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

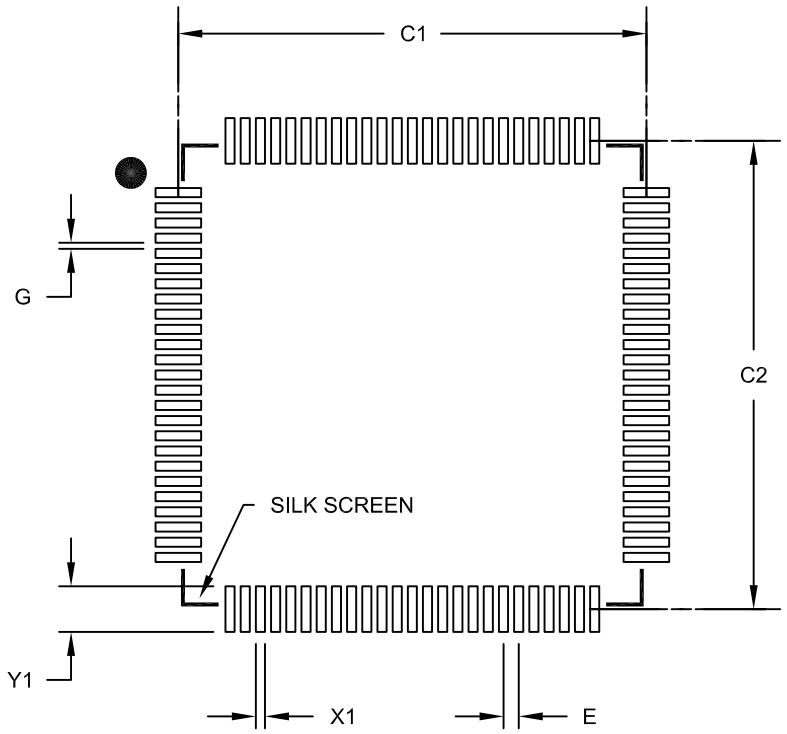
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-100B

100-Lead Plastic Thin Quad Flatpack (PF) - 14x14x1 mm Body 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		15.40	
Contact Pad Spacing	C2		15.40	
Contact Pad Width (X100)	X1			0.30
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2110B

NOTES: